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INTERNAL VISUAL INSPECTION OF QUARTZ CRYSTAL UNITS

ESCC Basic Specification No. 2043501

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1. **SCOPE**

This specification, to be read in conjunction with ESCC Basic Specification No. 20400, Internal Visual Inspection, contains additional specific requirements for Capacitors.

They shall apply to each component inspected.

2. **GENERAL REQUIREMENTS**

2.1 **APPLICABILITY**

The following criteria may not be varied or modified after commencing any inspection stage. Any ambiguity or proposed minor deviation shall be referred to the ESCC Executive for resolution and approval.

2.2 **PROCEDURE**

All components shall be submitted to examination immediately prior to sealing or encapsulation, or immediately after decapping, in an area where the standard of cleanliness is not less than that of the assembly area.

All items shall be examined in such a manner that a minimum of handling and movement of the component is involved.

2.3 **MAGNIFICATION**

All items shall be examined with a binocular or stereoscopic microscope under a magnification of X15 to X20.

2.4 **MOUNTING FIXTURES**

Suitable fixtures may be used to assist in the inspection process. They must not themselves cause damage to the device.

3. **DETAILED REQUIREMENTS**

3.1 **GENERAL**

A component shall be rejected if it exhibits one or more of the defects listed in any of the following paragraphs.

3.2 **QUARTZ ELEMENT DEFECTS**

(D = Quartz element diameter)

- (a) Cracked quartz element (see Figure 1).
- (b) Quartz element with scratch(es), the total length of which is greater than $D/3$ (see Figure 2).
- (c) Quartz element chipped more than 2% of total area (see Figure 3).
- (d) Quartz element notched such that future cracks are possible (see Figure 4).
- (e) Chip with crack starting from it.
- (f) Scratches presenting one or more chips.
- (g) Scratch(es) starting or ending at quartz element periphery.
- (h) Non-detachable chip.
- (i) Chip on quartz element periphery greater than 1% of quartz element surface.

- (j) Incorrect cutting (see Figure 5).

3.3 METALLISATION DEFECTS

- (a) Reduction in metallisation greater than 10% of metallised surface (see Figure 6).
- (b) Scratches across metallisation.
- (c) Scratches on metallisation greater than one-third of the electrode's diameter.
- (d) Total pin-hole surface greater than 0.2mm^2 (a pin-hole is a hole whose surface is greater than or equal to 0.1mm^2).
- (e) Bubbles and depressions.
- (f) Lifting of metallisation and peeling.
- (g) Oxidation.
- (h) Misalignment between the two metallised surfaces with d greater than $DE/5$ (see Figure 7).
- (i) Foreign materials.

3.4 HEADER DEFECTS AND PRESENCE OF FOREIGN MATERIAL (SEE FIGURE 8)

- (a) Any glass on the flange or side of the header.
- (b) Any quartz element or part of a quartz element on the flange or side of the header.
- (c) Gold or nickel plating showing evidence of blistering or flaking.
- (d) Any solder preform on the flange which still resembles a preform.
- (e) Posts bent more than 10 degrees.
- (f) Any metal shavings on the flange or side of the header longer than the width of the flange.
- (g) Bent or deformed header flanges.
- (h) Any metallic particle on top of the header which is larger than 25 microns and not firmly attached to the header.
- (i) Any non-metallic particle larger than 25 microns in the major dimension on top of the header or on the insulating glass between post and header.
- (j) Gold overlapping the seals.
- (k) Cracked or chipped glass seals.
- (l) Non-uniformity of finish or lead or post, particularly at the glass seal.
- (m) Nicks or bulges in the lead diameter outside stated lead tolerances.
- (n) Bubbles or an area of adjacent bubbles in the seal area larger than 12.5% of the seal area.
- (o) Foreign particles enclosed in the glass seal.
- (p) The minimum distance between the lead and the body shall be 0.13mm.
- (q) Lead tilted by more than 5 degrees.

3.5 ASSEMBLY DEFECTS

- (a) Crystal units with metal-plated quartz elements shall have intimate metal-to-metal continuity from lead to quartz element. Interference, friction, crimped or similar joining of parts, not reinforced by solder, welding, etc., shall not be acceptable (see Figure 9).
- (b) Eccentricity of quartz element with X_{\min} less than $X_{\max}/2$ (see Figures 10(a) and 10(b)).
- (c) Quartz element not aligned to within 10° of normal horizontal plane of the header.
- (d) Internal leads not within 10° of vertical and not uniform in length and construction.
- (e) Improper weld position of internal leads to post (see Figure 11):
 - A - weld spot placed partially on internal lead.
 - B - overlap between lower edge of internal lead and top of post less than 1 post diameter or 1mm, whichever is greater.

4. **FIGURES**

FIGURE 1 - CRACKED QUARTZ ELEMENT

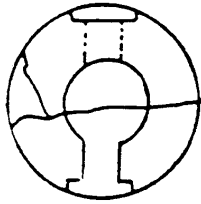
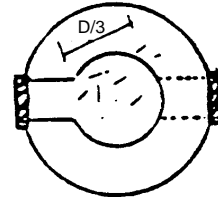


FIGURE 2 - QUARTZ ELEMENT WITH SCRATCHES



NOTES

1. Total length exceeding $D/3$.

FIGURE 3 - QUARTZ ELEMENT CHIPPED MORE THAN 2% OF TOTAL AREA

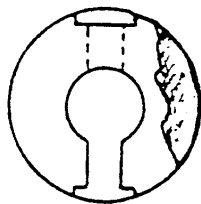


FIGURE 4 - QUARTZ ELEMENT NOTCHED SUCH THAT FUTURE CRACKS ARE POSSIBLE

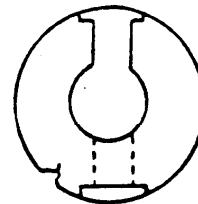


FIGURE 5 - INCORRECT CUTTING

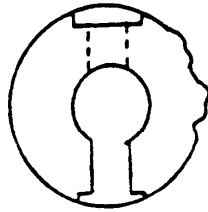


FIGURE 6 - REDUCTION IN METALLISATION

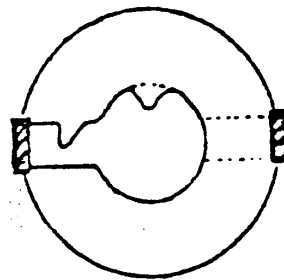


FIGURE 7 - MISALIGNMENT

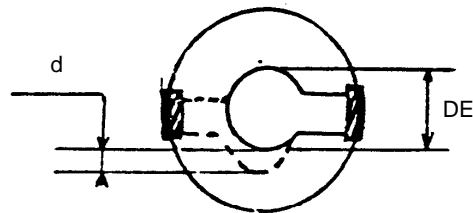
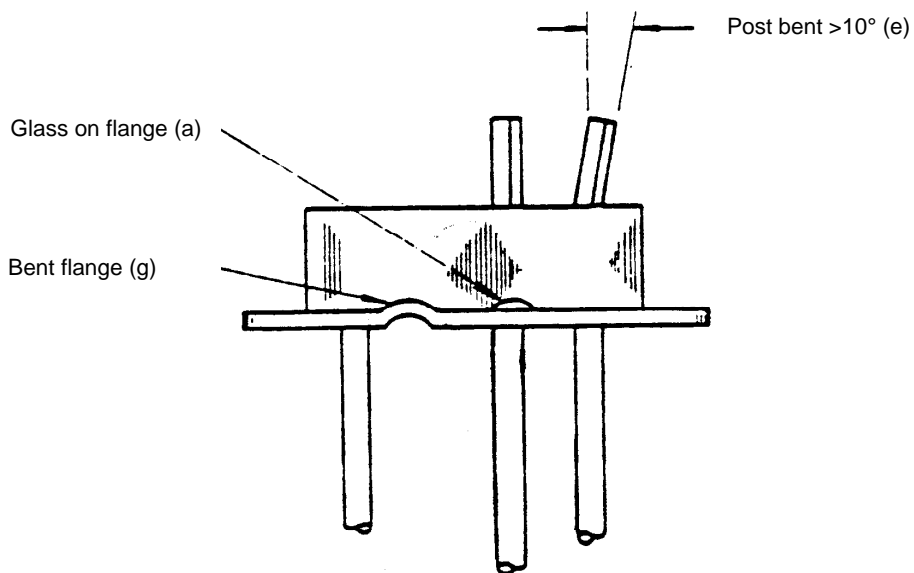
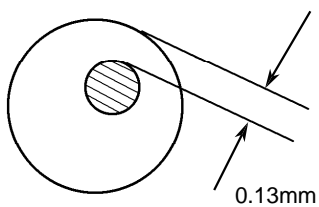


FIGURE 8 - HEADER DEFECTS



OFF-CENTRE LEADS (p)



LEAD TILT (q)

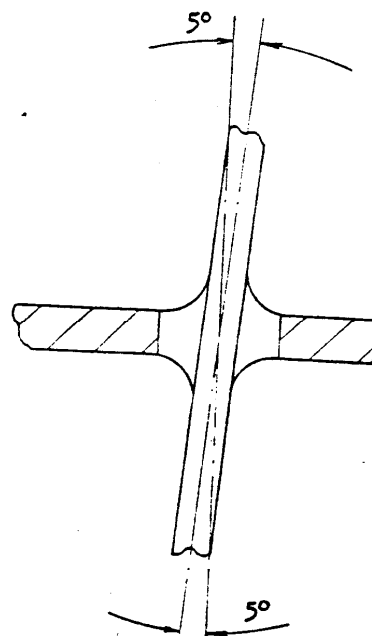


FIGURE 9 - INTERNAL LEAD TO QUARTZ ELEMENT JUNCTION

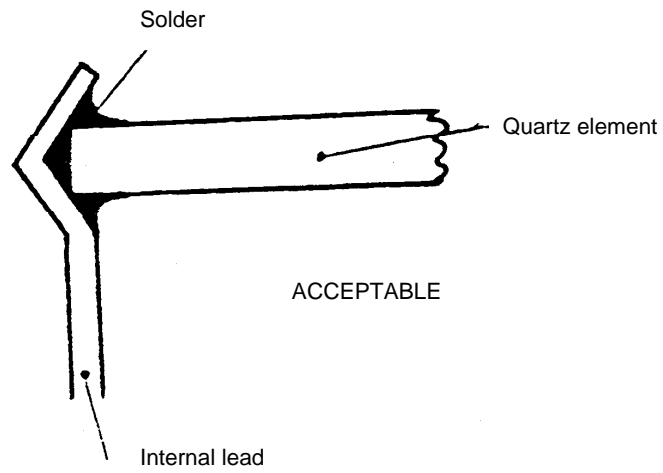


FIGURE 10(a) - ACCEPTED

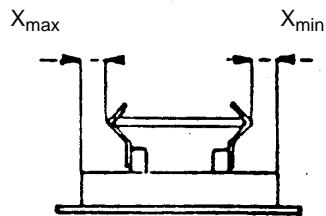


FIGURE 10(b) - REJECTED

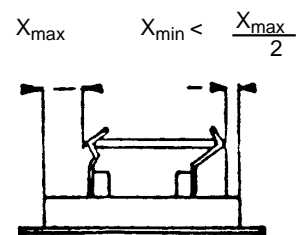


FIGURE 11 - IMPROPER WELD POSITION

